

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450
www.uspto.gov

JUDGE PATENT FIRM RIVIERE SHUKUGAWA 3RD FL. 3-1 WAKAMATSU-CHO NISHINOMIYA-SHI, HYOGO 662-0-035 JP JAPAN

COPY MAILED

DEC 0 7 2005

OFFICE OF PETITIONS

Applicant: Itakura et al. Appl. No.: 10/709,305 Filing Date: April 28, 2004

Title: SOLDER FILM MANUFACTURING METHOD, HEAT SINK FURNISHED WITH SOLDER FILM, AND SEMICONDUCTOR-DEVICE-AND-HEAT-SINK JUNCTION

Attorney Docket No.: 39.036 Pub. No.: US 2005/0089700 A1 Pub. Date: April 28, 2005

This is a decision on the request for a corrected patent application publication under 37 CFR 1.221(b), filed on June 28, 2005, for the above-identified application.

The request is granted.

The corrected patent application publication will be published in due course, unless the patent issues before the application is republished.

Inquiries relating to this matter may be directed to Mark Polutta at (571) 272-7709 (voice).

Mark O. Polutta

Office of Patent Legal Administration Office of the Deputy Commissioner for Patent Examination Policy